

**CRYSTAL OSCILLATOR (Programmable)
SPREAD SPECTRUM
OUTPUT: CMOS**



Product Number
SG-9101CA: X1G005301xxxx00
SG-9101CB: X1G005311xxxx00
SG-9101CE: X1G005321xxxx00
SG-9101CG: X1G005291xxxx00

SG-9101 series

- Frequency range : 0.67 MHz to 170 MHz (1 ppm Step)
- Supply voltage : 1.62 V to 3.63 V
- Function : Output enable (OE) or Standby (\overline{ST})
- Configurable spread spectrum settings:
 2 kinds of spread type, 6 kinds of spread width
 4 kinds of modulation frequency, 3 kinds of spread profile
- PLL technology to enable short lead time
- Available field oscillator programmer "SG-Writer II"



Specifications (characteristics)

Item	Symbol	Specifications				Conditions/Remarks	
Supply voltage	V _{CC}	1.80 V Typ.		2.50 V Typ.	3.30 V Typ.		-
		1.62 V to 1.98 V	1.98 V to 2.20 V	2.20 V to 2.80 V	2.70 V to 3.63 V		
Output frequency range	f _o	0.67 MHz to 170 MHz					
Storage temperature	T _{stg}	-40 °C to +125 °C				Storage as single product.	
Operating temperature	T _{use}	-40 °C to +85 °C					
		-40 °C to +105 °C					
Frequency tolerance ^{*1}	f _{tol}	±50 × 10 ⁻⁶				Average frequency of 1s gate time.	
Current consumption	I _{CC}	3.4 mA Max.	3.5 mA Max.	3.6 mA Max.	3.7 mA Max.	T _{use} = +105 °C	No load, f _o = 20 MHz
		2.9 mA Typ.		3.0 mA Typ.	3.2 mA Typ.	T _{use} = +25 °C	
		5.7 mA Max.	6.0 mA Max.	6.9 mA Max.	8.3 mA Max.	T _{use} = +105 °C	No load, f _o = 170 MHz
		4.9 mA Typ.		5.9 mA Typ.	7.0 mA Typ.	T _{use} = +25 °C	
Output disable current	I _{dis}	3.4 mA Max.	3.4 mA Max.	3.5 mA Max.	3.7 mA Max.	OE = GND, f _o = 170 MHz	
Standby current	I _{std}	0.9 μA Max.	1.0 μA Max.	1.5 μA Max.	2.5 μA Max.	T _{use} = +105 °C	\overline{ST} = GND
		0.3 μA Typ.	0.4 μA Typ.	0.5 μA Typ.	1.1 μA Typ.	T _{use} = +25 °C	
Symmetry	SYM	45 % to 55 %				50 % V _{CC} Level	
Output voltage (DC characteristics)	V _{OH}	90 % V _{CC} Min.				I _{OH} /I _{OL} Conditions [mA]	
	V _{OL}	10 % V _{CC} Max.					
		Rise/Fall time	V _{CC}	*A	*B	*C	*D
		Default (f _o > 40 MHz), Fast	I _{OH}	-2.5	-3.5	-4.0	-5.0
			I _{OL}	2.5	3.5	4.0	5.0
		Default (f _o ≤ 40 MHz)	I _{OH}	-1.5	-2.0	-2.5	-3.0
			I _{OL}	1.5	2.0	2.5	3.0
		Slow	I _{OH}	-1.0	-1.5	-2.0	-2.5
			I _{OL}	1.0	1.5	2.0	2.5
*A : 1.62 V to 1.98 V, *B : 1.98 V to 2.20 V, *C : 2.20 V to 2.80 V, *D : 2.70 V to 3.63 V							
Output load condition	L _{CMOS}	15 pF Max.				-	
Input voltage	V _{IH}	70 % V _{CC} Min.				OE or \overline{ST}	
	V _{IL}	30 % V _{CC} Max.					
Rise time / Fall time	Default / Fast / Slow	tr/tf	3.0 ns Max.		f _o > 40 MHz		20 % - 80 % V _{CC} , L _{CMOS} = 15 pF
			6.0 ns Max.		f _o ≤ 40 MHz		
			3.0 ns Max.		f _o = 0.67 MHz to 170 MHz		
			10.0 ns Max.		f _o = 0.67 MHz to 20 MHz		
Output disable time (OE)	tstp_oe	1 μs Max.				Measured from the time OE or \overline{ST} pin crosses 30 % V _{CC}	
Output disable time (ST)	tstp_st	1 μs Max.				Measured from the time OE pin crosses 70 % V _{CC}	
Output enable time (OE)	tsta_oe	1 μs Max.				Measured from the time OE pin crosses 70 % V _{CC}	
Output enable time (ST)	tsta_st	3 ms Max.				Measured from the time \overline{ST} pin crosses 70 % V _{CC}	
Start-up time	t _{str}	3 ms Max.				Measured from the time V _{CC} reaches its rated minimum value, 1.62 V	
Frequency aging	f _{age}	This is included in frequency tolerance specification.				+25 °C, first year	

*1 Frequency tolerance includes initial frequency tolerance, frequency / temperature characteristics, frequency / voltage coefficient, frequency / load coefficient and frequency aging (+25 °C, 1 year).

Pin description

Pin	Name	I/O type	Function	
1	OE	Input	Output enable	High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), only output driver is disabled.
	\overline{ST}	Input	Standby	High ^{*2} : Specified frequency output from OUT pin Low: Out pin is low (weak pull down), Device goes to standby mode. Supply current reduces to the least as I _{std} .
2	GND	Power	Ground	
3	OUT	Output	Clock output	
4	V _{CC}	Power	Power supply	

*2 Please do not use the OE/ST terminal in the open state.



Product Name

SG-9101CG 170.000000MHz C 20 P H A A A
① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩

- ① Model ② Package type ③ Frequency
- ④ Spread type ⑤ Spread width
- ⑥ Function ⑦ Operating temperature
- ⑧ Modulation frequency ⑨ Spread profile
- ⑩ Rise/Fall time

② Package type	
CG	2.5 mm × 2.0 mm
CE	3.2 mm × 2.5 mm
CB	5.0 mm × 3.2 mm
CA	7.0 mm × 5.0 mm

④ Spread type	
C	Center spread
D	Down spread

⑤ Spread width		
	Center spread	Down spread
02	±0.25 %	
05	±0.5 %	-0.5 %
07	±0.75 %	
10	±1.0 %	-1.0 %
15	±1.5 %	-1.5 %
20	±2.0 %	-2.0 %
30		-3.0 %
40		-4.0 %

⑧ Modulation frequency	
A	25.4 kHz (Default)
B	12.7 kHz
C	8.5 kHz
D	6.3 kHz

⑨ Spread profile	
A	Hershey-kiss (Default)
B	Sine-wave
C	Triangle

⑥ Function	
P	Output enable
S	Standby

⑩ Rise/Fall time	
A	Default
B	Fast
C	Slow

⑦ Operating temperature	
G	-40 °C to +85 °C
H	-40 °C to +105 °C

External dimensions

(Unit: mm)



Footprint (Recommended)

(Unit: mm)



Notes:

In order to achieve optimum jitter performance, the 0.1 μF capacitor between V_{CC} and GND should be placed. It is also recommended that the capacitors are placed on the device side of the PCB, as close to the device as possible and connected together with short wiring pattern.

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